



CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to: Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450, on the below date:

Date: August 18, 2004 Name: Joseph W. Flerlage Signature:

BRINKS
HOFER
GILSON
& LIONE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln. of: Heinrich Ollendorf et al.

Appln. No.: 10/777,608

Filed: February 11, 2004

For: POST METAL CHEMICAL MECHANICAL
POLISHING DRY CLEANING

Attorney Docket No: 2003 P 54807 US
(BHGL No. 10808/119)

Examiner:

Art Unit: 2812

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL

Sir:

Attached is/are:

- ☒ Transmittal Letter (in duplicate); Information Disclosure Statement (in duplicate); Form PTO-1449; Copy of Cited References
- ☒ Return Receipt Postcard

Fee calculation:

- ☒ No additional fee is required.
- ☐ Small Entity.
- ☐ An extension fee in an amount of \$_____ for a _____-month extension of time under 37 C.F.R. § 1.136(a).
- ☐ A petition or processing fee in an amount of \$_____ under 37 C.F.R. § 1.17(_____).
- ☐ An additional filing fee has been calculated as shown below:

					Small Entity			Not a Small Entity	
	Claims Remaining After Amendment		Highest No. Previously Paid For	Present Extra	Rate	Add'l Fee	or	Rate	Add'l Fee
Total		Minus			x \$9=			x \$18=	
Indep.		Minus			x 43=			x \$86=	
First Presentation of Multiple Dep. Claim					+\$145=			+\$290=	
					Total	\$		Total	\$

Fee payment:

- ☐ A check in the amount of \$_____ is enclosed.
- ☐ Please charge Deposit Account No. 23-1925 in the amount of \$_____. A copy of this Transmittal is enclosed for this purpose.
- ☐ Payment by credit card in the amount of \$_____ (Form PTO-2038 is attached).
- ☒ The Director is hereby authorized to charge payment of any additional filing fees required under 37 CFR § 1.16 and any patent application processing fees under 37 CFR § 1.17 associated with this paper (including any extension fee required to ensure that this paper is timely filed), or to credit any overpayment, to Deposit Account No. 23-1925.

Respectfully submitted,

Date

August 18, 2004

Joseph W. Flerlage (Reg. No. 52,897)



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August 18, 2004

Date of Deposit

Joseph W. Flerlage, Reg. 52,897

Name of Applicant, Assignee or
Registered Representative

Signature

Date of Signature

Our Case No.: 2003 P 54807 US
(BHGL No. 10808/119)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Heinrich Ollendorf et al.

Serial No.: 10/777,608

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For: POST METAL CHEMICAL
MECHANICAL POLISHING DRY
CLEANING

Examiner:

Group Art Unit No.: 2812

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Alexandria, VA 22313-1450

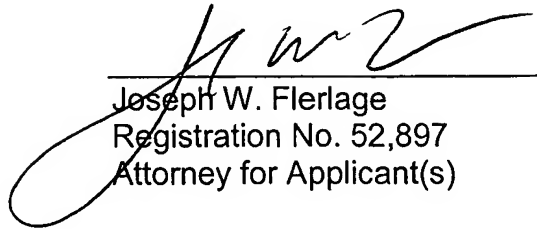
Dear Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56, it is respectfully requested that this Information Disclosure Statement be entered and the documents listed below and on the attached Form PTO-1449 be considered by the Examiner and

Applicant(s) respectfully request that the listed documents be made of record in the present case.



Respectfully submitted,



Joseph W. Flerlage
Registration No. 52,897
Attorney for Applicant(s)

BRINKS HOFER GILSON & LIONE
P.O. Box 10395
Chicago, IL 60610
(312) 321-4200



FORM PTO-1449	SERIAL NO. 10/777,608	CASE NO. 2003 P 54807 US (BHGL No. 10808/119)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT (use several sheets if necessary)	FILING DATE February 11, 2004	GROUP ART UNIT 2812
APPLICANT(S): Heinrich Ollendorf et al.		

EXAMINER INITIAL	OTHER ART – NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.	
	A1	Kelly H. Block, Heather L. Rayle, "Integration of CMP with Low-k Materials", Semiconductor International, Entegris, Reed Business Information, a division of Reed Elsevier Inc., (June 1, 2002), 7 pages.
	A2	Maria A. Lester, Associate Editor, "Post-CMP Cleaning Enhanced on Ploy-Si Film", Semiconductor International, Focus Dry, Reed Business Information, a division of Reed Elsevier Inc., (July 1, 2002), 2 pages.
	A3	Souvik Banerjee, Andrea Via, Harlan F. Chung, Robert J. Small, "Combining Aqueous and Cryogenic Post-CMP Cleaning", Semiconductor International, Solid State Equipment Corporation, Reed Business Information, a division of Reed Elsevier Inc., (February 1, 2003), 7 pages.
	A4	Michael R. Oliver, "Chemical Mechanical Polishing", Semiconductor International, ASML, Reed Business Information, a division of Reed Elsevier Inc., (June 1, 2003), 2 pages.

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



made of record. Copies of the listed documents required by 37 C.F.R. § 1.98(a)(2) are enclosed for the convenience of the Examiner.

The references now cited are the following:

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)
Kelly H. Block, Heather L. Rayle, "Integration of CMP with Low-k Materials", Semiconductor International, Entegris, Reed Business Information, a division of Reed Elsevier Inc., (June 1, 2002), 7 pages.
Maria A. Lester, Associate Editor, "Post-CMP Cleaning Enhanced on Ploy-Si Film", Semiconductor International, Focus Dry, Reed Business Information, a division of Reed Elsevier Inc., (July 1, 2002), 2 pages.
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In accordance with 37 C.F.R. § 1.97(g),(h), this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed to be an admission that the information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b).

This Information Disclosure Statement is being filed prior to the receipt of the first Official Action reflecting an examination on the merits and hence is believed to be timely filed in accordance with 37 C.F.R. § 1.97(b). No fees are believed to be due in connection with filing of this Information Disclosure Statement, however, should any fees under 37 C.F.R. §§ 1.16 to 1.21 be deemed necessary for any reason relating to these material, the Commissioner is hereby authorized to deduct said fees from Brinks Hofer Gilson & Lione Deposit Account No. 23-1925. A duplicate copy of this document is enclosed.